

**METHOD OF AND APPARATUS FOR CONTROLLING PROBE TIP SANDING IN  
SEMICONDUCTOR DEVICE TESTING EQUIPMENT**

5 ABSTRACT OF THE DISCLOSURE

In a method of and apparatus for controlling probe tip sanding in semiconductor device testing equipment, resistance values of pads of a probed chip are measured and stored. If a maximum resistance value among the stored resistance values is greater than a contact resistance reference value, a consecutive fail counting value and an accumulated fail counting value are increased. An automatic sanding command is generated to activate automatic sanding of a probe tip, when at least one of the consecutive fail counting value and the accumulated fail counting value is greater than a respective counting reference value. In this manner, false negative readings in the testing of semiconductor devices as the result of increased contact resistance between a probe tip and a pad in an EDS test are reduced and therefore device yield is improved.

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